IN THE CLAIMS:

Please amend the claims as follows:

1. (currently amended) A method for dispensing a single ligament of fluid with an inkjet dispenser comprising:

ejecting a first quantity of said fluid from said inkjet dispenser toward a substrate; and

ejecting subsequent quantities ~~a second quantity~~ of said fluid from said inkjet dispenser toward said substrate;

wherein said subsequent quantities ~~second quantity~~ of fluid [[is]] are ejected from said inkjet dispenser ~~at a frequency sufficient~~ such that said first quantity of said fluid and said subsequent quantities ~~second quantity~~ of said fluid form a single, continuous ligament of said fluid between said inkjet dispenser and ~~prior to contacting~~ said substrate.

2. (currently amended) The method of claim 1, further comprising ~~reining in~~ reducing a necking phenomena of said fluid.

3. (currently amended) The method of claim 2, wherein said ~~reining in~~ reducing a necking phenomena comprises increasing a viscosity of said fluid.

4. (currently amended) The method of claim 2, wherein said ~~reining in~~ reducing a necking phenomena comprises decreasing a surface tension of said fluid.

5. (currently amended) The method of ~~claim 4~~ claim 1, wherein said inkjet dispenser is disposed in an inkjet printer configured to form two-dimensional characters.

6. (original) The method of claim 5, wherein said fluid comprises ink.

7. (original) The method of claim 1, wherein said inkjet dispenser is disposed in a solid freeform fabrication apparatus.

8. (original) The method of claim 7, wherein said fluid comprises an object build material.

9. (original) The method of claim 7, wherein said fluid comprises an object support material.

10. (original) The method of claim 1, wherein said inkjet dispenser is disposed in a circuit formation apparatus.

11. (original) The method of claim 10, wherein said fluid comprises one of a conductive circuit build material, a semi-conductive build material, or a dielectric build material.

12. (original) The method of claim 10, wherein said single ligament of fluid contacts said substrate to form a circuit component.

13. (original) The method of claim 12, wherein said circuit component comprises one of a transistor, a trace, a capacitor, a resistor, an antenna, a display, or a radiofrequency identification tag.

14. (currently amended) The method of ~~claim 2~~ claim 1, wherein said fluid comprises an adhesive or binder.

15. (currently amended) A method for dispensing a single ligament of fluid from a thermal inkjet dispenser comprising:

ejecting a first quantity of said fluid having a head and a tail from said thermal inkjet dispenser toward a substrate; and

ejecting subsequent quantities ~~a second quantity~~ of said fluid having at least a head from said thermal inkjet dispenser toward said substrate;

wherein said subsequent quantities ~~second quantity~~ of fluid [[is]] are ejected from said thermal inkjet dispenser ~~at a frequency sufficient~~ such that said head of each of said subsequent quantities ~~second quantity~~ of fluid catches said tail of a preceding ~~said first~~ quantity of fluid ~~prior to contacting said substrate,~~ thereby forming a single, continuous ligament of said fluid between said dispenser and said substrate.

16. (original) The method of claim 15, further comprising choosing said fluid to have a viscosity above 2 centipoise at an operating temperature of said inkjet dispenser.

17. (original) The method of claim 15, further comprising choosing said fluid to have a surface tension below 30 dyne/centimeter.

18-68. (cancelled)

69. (new) A method for dispensing a single ligament of fluid with an inkjet dispenser comprising:

ejecting a first quantity of said fluid from said inkjet dispenser toward a substrate;

refilling a firing chamber of said dispenser with a second quantity of fluid less than said first quantity; and

ejecting said second quantity of said fluid from said inkjet dispenser toward said substrate;

wherein said second quantity of fluid is ejected from said inkjet dispenser such that said first quantity of said fluid and said second quantity of said fluid join to form a single ligament of said fluid prior to contacting said substrate.

70. (new) The method of claim 69, wherein said refilling a firing chamber with a second quantity of fluid less than said first quantity is performed by increasing backpressure in said firing chamber.

71. (new) The method of claim 69, wherein said refilling a firing chamber with a second quantity of fluid less than said first quantity is performed by increasing a viscosity of said fluid.

72. (new) The method of claim 69, wherein said refilling a firing chamber with a second quantity of fluid less than said first quantity is performed by decreasing impedance of an orifice of said firing chamber.